

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

**LISTING OF CLAIMS:**

1. – 31. (Cancelled).

32. (Currently amended) A substrate for semiconductor packages, said substrate having an insulating supporting member and plural sets of wirings formed on one side of said insulating supporting member, and further comprising:

a semiconductor device mounting region and a resin-sealing semiconductor package region outside of said semiconductor device mounting region,

wherein said wirings comprise a predetermined wiring pattern including wire-bonding terminals and external connection terminals,

wherein said wire bonding terminals are provided in said semiconductor package region and said external connection terminals are provided only within said semiconductor device mounting region,

wherein openings are provided in said insulating supporting member at points where said external connection terminals are formed, reaching said external connection terminals, the external connection terminals providing a cap on said openings, and

wherein plural sets of said semiconductor device mounting region and said semiconductor package region are formed on said insulating supporting member, ~~and members~~

wherein said plurality of said semiconductor device mounting regions and ~~semiconductor~~ semiconductor package regions have blocks of said wirings, each

having a same wiring pattern.

33. – 34. (Cancelled).

35. (Previously presented) The substrate for semiconductor packages according to claim 32, wherein said wire-bonding terminal comprises a nickel layer and a gold plate layer on its surface.

36. (Previously presented) The substrate for semiconductor packages according to claim 32,

wherein said external connection terminals are arranged in a grid pattern at positions corresponding to a semiconductor device mounting region of said substrate.

37. (Previously presented) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for semiconductor packages according to claim 32 by employing a die-bonding material,

electrically connecting each of the semiconductor devices with the wire-bonding terminals by wire-bonding,

sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for semiconductor packages and said sealing resin in

one operation to be separated into the individual semiconductor package.

38. – 40. (Cancelled).

41. (Previously presented) The substrate for semiconductor packages according to claim 32, wherein said plural sets of wirings are formed only on said one side of said insulating supporting member.

42. (New) The substrate for semiconductor packages according to claim 32, wherein said external connection terminals completely block said openings.

43. (New) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for semiconductor packages according to claim 42 by employing a die-bonding material,

electrically connecting each of the semiconductor devices with the wire-bonding terminals by wire-bonding,

sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for semiconductor packages and said sealing resin in one operation to be separated into the individual semiconductor package.

44. (New) The substrate for semiconductor packages according to claim 32, wherein said plural sets of wirings are provided on a surface of said insulating support member.

45 (New) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for semiconductor packages according to claim 44 by employing a die-bonding material,

electrically connecting each of the semiconductor devices with the wire-bonding terminals by wire-bonding,

sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for semiconductor packages and said sealing resin in one operation to be separated into the individual semiconductor package.

46. (New) The substrate for semiconductor packages according to claim 32, wherein said semiconductor device mounting region is provided at said one side of said insulating support member.

47. (New) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for semiconductor packages according to

claim 46 by employing a die-bonding material,  
electrically connecting each of the semiconductor devices with the wire-bonding terminals by wire-bonding,  
sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;  
forming solder bumps on said external connection terminals; and  
cutting said substrate for semiconductor packages and said sealing resin in one operation to be separated into the individual semiconductor package.

48. (New) The substrate for semiconductor packages according to claim 46, wherein said external connection terminals completely block said openings.

49. (New) The substrate for semiconductor packages according to claim 46, wherein said plural sets of wirings are provided on a surface of said insulating support member.

50. (New) The substrate for semiconductor packages according to claim 32, wherein said openings extend completely through said insulating supporting member.

51. (New) The substrate for semiconductor packages according to claim 50, wherein said semiconductor device mounting region is provided at said one side of said insulating support member.

52. (New) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for semiconductor packages according to claim 51 by employing a die-bonding material,

electrically connecting each of the semiconductor devices with the wire-bonding terminals by wire-bonding,

sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for semiconductor packages and said sealing resin in one operation to be separated into the individual semiconductor package.

53. (New) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for semiconductor packages according to claim 50 by employing a die-bonding material,

electrically connecting each of the semiconductor devices with the wire-bonding terminals by wire-bonding,

sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for semiconductor packages and said sealing resin in one operation to be separated into the individual semiconductor package.